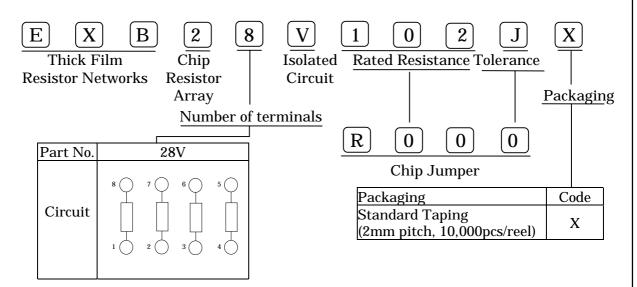


(RCWV)

Subject	Spec. No.
Chip Resistor Array PRODUCT SPECIFICATION FOR INFORMATION	151-EXB-28V02DE
Part No.	
EXB28V	9-2

Item	Rated Valu	ie	Explanation			
Maximum overload voltage	overload v overload v Maximum	oltage, th oltage. overload v	$.5 \times E$ . When the volume value shown below voltage: 100V verload current 2A	0		
Resistance tolerance	S	J ±	olerance for resistanc 5% hip Jumper	e		
Range of rated resistance for manufacture	Tole		esistance range .0 Ω to 1.0 MΩ	Series E-24	8	

### 4. Explanation of part number



## 5. Appearance & Construction

Item	Specifications	Explanation
Appearance & Construction	<ul> <li>that do not fa unevenness, fla</li> <li>2. The electrode dimensions. Th unevenness, fla</li> <li>3. The electrode s resistive element</li> <li>4. Substrate should</li> </ul>	lement should be covered with protective coating ade easily. The surface of coating should avoid aw, pinhole and discoloration. should be printed uniformly, as shown in the plating should not fade easily, and should avoid aw, pinhole, projection and discoloration. should be connected electrically, mechanically to nt. d not have chipping, flaw, flash and crack. Details criteria shall be as described in attached sheet

Subject				Spec. No.
Chin Resistor	Array PRODUCT S	PECIFICATIO	ON FOR INFORMATION	151-EXB-28V02D
Part No.	initity incodecing			
	FX	B28V		9-3
As far as there	shall be not designat	tion especially	, the following test and mea	asurement shall be
operated und	er normal temperatu	ure(5 °C to 35	°C), normal humidity(45 °	%RH to 85 %RH),
normal atmos	pheric pressure(86 k	Pa to 106 kPa)		
normal actilos	pheric pressure (00 k	i u to 100 ki u)		
6. Performance	Specification			
Itom	Specification		Test methods	
Item	Resistor	Jumper	Test methods	
DC resistance	DC resistance v	alue shall be	e Measuring voltage: refer to	o JIS-C5201-1
DC resistance	within the specifie	d tolerance	At 20 °C, 65 %RH	
	Resistance	TCR	Natural resistance change	ge per temperatu
	$< 10\Omega$	$^{+600}_{-100} \times 10^{-6} / ^{\circ}C$	degree centigrade.	
		$00 \times 10^{-6} / ^{\circ}C$	$TCR = \frac{R_2 - R_1}{R_1 \times (t_2 - t_1)}$	
Temperature coefficient				
			$R_1$ : Resistance value at	treference
			temperature(t <sub>1</sub> )	
			$R_2$ : Resistance value at	ttest
			temperature( $t_2$ )	C
			$t_2 - t_1 = 100$ °C, $t_1 = 25$ ° Resistors shall be applied	
Overload	±(2 %+0.1 Ω)	Less than	voltage for 5 seconds.	2.5 times the rate
Overload	$\pm (2 70 \pm 0.1 22)$	50 mΩ	Maximum over load voltage	ve shall be 100 V
			Resistors shall be subjected	
		1	2.5 times the rated vol	
Intermittent	±(5 %+0.1 Ω)	Less than	second with pause of 2	
overload		50 mΩ	tests.	
			Maximum over load voltag	ge shall be 100 V
Dielectric	No evidence of flag	shover,	AC 100V between substra	ate and terminati
Withstanding	mechanical damag	ge, arcing or	for 1 minute.	
)	insulation breakdo	own.		
Insulation	Min. 1,000 MΩ		Insulation resistance betw	
Resistance			termination shall be meas	ured at DC 100V.
7. Mechanical c				
Item	Specification		-Test methods	
	Resistor	Jumper		
Terminal strength	min. 4.9N		Copper plate: t=0.4 mm	
)			Pull speed: 10 mm/s	
	of No mechanical dat	mage	Substrate: Glass epoxy(t =	1.6 mm)
Bend strength the face plating		Less than	-Span: 90 mm	
	±(1 %+0.05 Ω)	Less than	Bending distance: 3 mm (1	() coconde)

the face plat	ing	±(1 %+0.05 Ω)	Less than $50 \text{ m}\Omega$	Bending distance: 3 mm (10 seconds)
Solderability	I	Termination shou uniformly with solo (min. 95 % coverag	uer.	Resistors shall be dipped in the melted solder bath at 235 °C $\pm$ 5 °C for 2 s $\pm$ 0.5 s. Flux shall be removed from the surface of termination with clean organic solvent.

Subject		Spec. No.
Chip Resistor Array	PRODUCT SPECIFICATION FOR INFORMATION	151-EXB-28V02DE

## EXB28V

Item	Specification	-	Test methods	
	Resistor	Jumper		
Resistance to soldering heat	±(1 %+0.05 Ω)		Resistors shall be dipped i bath at 270 °C $\pm$ 5 °C for 10	
Vibration	±(1 %+0.05 Ω)	Less than 50 mΩ	Resistors shall be subj vibration having as doubl mm for 2 hours in eac perpendicular directions fo The vibration frequency uniformly 10 Hz to 55 Hz a traversing for 1 minute.	e amplitude of 1.5 ch three mutually r total 6 hours. shall be varied
	Without distinct o	leformation in	Solvent solution: Isopropyl	alcohol
	appearance		(1) Dipping 10 hours $\pm 1$	hour, dry in room
Solvent resistance	±(0.5 %+0.05 Ω)	Less than 50 mΩ	condition for 30 min ± 10 (2) Ultrasonic wave washir (0.3 W/cm,28 kHz) Dry in room condition	0 min. ng: 5 min ± 1 min

# 8. Environmental Test

Item Specification			Test methods
Item	Resistor	Jumper	Test methods
Low temperature exposure	±(1 %+0. 05 Ω)	Less than 50 mΩ	Resistors shall be exposed at -55 °C $\pm$ 3 °C for 1000 hours $^{+48}_{0}$ hours
Low temperature operating	±(1 %+0.05 Ω)	Less than 50 mΩ	Resistors shall be placed at -65 °C $\pm$ 5 °C for 1.5hours. After applying RCWV for 45 minutes, resistors shall be exposed in room condition for 8 hours $\pm$ 1 hour.
Endurance at upper category temperature	±(1 %+0.05 Ω)	Less than 50 mΩ	Resistors shall be exposed at +125 °C $\pm$ 3 °C for 1000 hours $^{+48}_{0}$ hours.
Temperature cycling	±(1 %+0.05 Ω)	Less than 50 mΩ	-55 °C $\pm$ 3 °C, 30 minutes $\uparrow\downarrow$ Nominal temp., 30minutes 25cycles $\uparrow\downarrow$ +125 °C $\pm$ 3 °C, 30minutes
Humidity (Steady state)	±(1 %+0.05 Ω)	Less than 50 mΩ	Resistors shall be exposed at 60 °C ± 2 °C and 90 % to 95 % relative humidity in a humidity test chamber for 1000 hours $^{+48}_{-0}$ hours.
Salt spray	±(1 %+0.05 Ω)	Less than 50 mΩ	Spray 5 wt% $\pm$ 1 wt% salt water for 96 hours $\pm$ 4 hours at 35 °C $\pm$ 2 °C
Endurance at 70 °C	±(3 %+0.1 Ω)	Less than 50 mΩ	Resistors shall be exposed at 70 °C $\pm$ 2 °C for 1000 hours $_{0}^{+48}$ hours. During this time, the rated voltage shall be applied intermittently for 1.5 hours ON, 0.5 hour OFF.
Load life in Humidity	±(3 %+0.1 Ω)	Less than 50 mΩ	Resistor shall be exposed at 60 °C $\pm$ 2 °C and 90 % to 95 % relative humidity for 1000 hours $_{0}^{+48}$ hours. During this time, the rated voltage shall be applied intermittently for 1.5 hours ON, 0.5 hour OFF.

Subject			Spec. No.
Chip Resistor Array PRODUCT SPECIFICATION FOR INFORMATION		151-EXB-28V02DE	
Part No.			
	EXB28V		9-5
9. Other character	eristics		
Item	Specification	Test methods	
Surface temperature rise	Less than 30 °C	Resistor shall be mount substrate (t = 1.0 mm). A element shall be applied rise at the center of resisto However, applied voltage max. overload voltage.	power of 0.031 W / l. The temperature or is measured.

# 10. Resistance value marking

No marking.

Subject	Spec. No.
Chip Resistor Array PRODUCT SPECIFICATION FOR INFORMATION	151-EXB-28V02DE
Part No.	
EXB28V	9-6
11. Notice for use	
Notice for use	
(1)This specification shows the quality and performance of the product in a unit	
adoption, be sure to evaluate and verify the product mounting it in your produ (2)We take no responsibility for troubles caused by the product usage that is r specification.	
<ul> <li>(3)In traffic transportation equipment (trains, cars, traffic signal equipment, aerospace equipment, electric heating appliances, combustion a rotating equipment, disaster and crime preventive equipment, etc. in cases that the failure of this product gives serious damage to human life and others, and ensure safety by studying the following items to</li> <li>Ensure safety as the system by setting protective circuits and protective e</li> </ul>	and gas equipment, where it is forecast use fail-safe design
• Ensure safety as the system by setting such redundant circuits as do not	
single failure. (4)When a dogma shall be occurred about safety for this product, be sure to inform your technical examination.	n us rapidly, operate
<ul><li>(5)The products in this specification are tended for use in general standard apple electric equipment (AV products, household electric appliances, office equipmer communication equipment, etc.); hence, they do not take the use under the environments into consideration.</li><li>Accordingly, the use in the following special environments, and such environment affect the performance of the products; prior to use, verify the performant thoroughly.</li></ul>	ent, information and ne following special onmental conditions
1) Use in liquids such as water, oil, chemical and organic solvent.	
<ol> <li>2) Use under direct sunlight or in outdoor or dusty atmospheres</li> <li>3) Use in places full of corrosive gases such as sea breeze, Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, a</li> <li>4) Use in environment with large static electricity or strong electromagnetic w</li> <li>5) Where the product is close to a heating component, or where an inflammable chloride wire is arranged close to the product.</li> <li>6) Where the resistor is sealed or coated with resin , etc.</li> <li>7) Where water or a water-soluble detergent is used in flux cleaning after solde</li> </ol>	/aves. e such as a polyvinyl
attention to water-soluble flux.)	, III.9 (Pa) Par
<ul> <li>(6)If transient load (heavy load on a short time) like pulse is expected to be evaluation and confirmation test with resistors actually mounted on your ow load of more than rated power is applied under the load condition at steady s performance and/or reliability of resistor. Never exceed the rated power. When the product shall be used under special condition, be sure to ask us in action (7)Halogen type (chlorine type, bromine type, etc.) or other high-activity flux is not the residue may affect performance or reliability of resistors.</li> </ul>	vn board. When the state, it may impair dvance. not recommended as
(8)When soldering with soldering iron, never touch the body of the chip resister soldering iron. When using a soldering iron with a tip at high temperature, a short as possible. (Three seconds or less up to 350 °C)	
(9)Avoid physical shock to the resistor and nipping of the resistor with hard too tweezers) as it may damage protective firm or the body of resistor and m performance.	
(10)Reflow soldering method shall apply to this product in principle.	

Subject	Spec. No.
Chip Resistor Array PRODUCT SPECIFICATION FOR INF	ORMATION 151-EXB-28V02DE
Part No.	
EXB28V	9-7
12 Storage method	

#### 12. Storage method

If the product is stored in the following environments and conditions, the performance and solderability may be badly affected. Avoid the storage in the following environments.

- (1) Storage in places full of corrosive gases such as sea breeze,  $Cl_2$ ,  $H_2S$ ,  $NH_3$ ,  $SO_2$ , and  $NO_X$
- (2) Storage in places exposed to direct sunlight
- (3) Storage in places outside the temperature range of 5  $^{\circ}C$  to 35  $^{\circ}C$  and humidity range of 45 %RH to 85 %RH
- (4) Storage over a year after our delivery (This item also applies to the case where the storage method specified in item (1) to (3) has been followed.)

### 13. Low and regulation

- (1) No ODCs or other ozone-depleting substances that are subject to regulation under the Montreal Protocol are used in our manufacturing processes, including in the manufacture of this product.
- (2) All materials used in this product are existing chemical substances recognized under "lows on examination of chemical substances and regulations of manufacturing and others."
- (3) None of the materials used in this product contain the designated incombustible bromic substances, PBBOs and PBBs.
- (4) Please contact us to obtain a notice as to whether this product has passed inspection under review criteria primarily based on Foreign Exchange and Foreign Trade Control Laws, and appended table in the Export Control Laws.
- 14. Period of validity for specification

If there is not an offer by letter by 3 months before term of validity, term of validity shall be extended every one year.

When you confirm revision of this specification while it is in effect, the previous, unrevised version shall lose its validity.

### 15. Production Place

Production Country :Japan

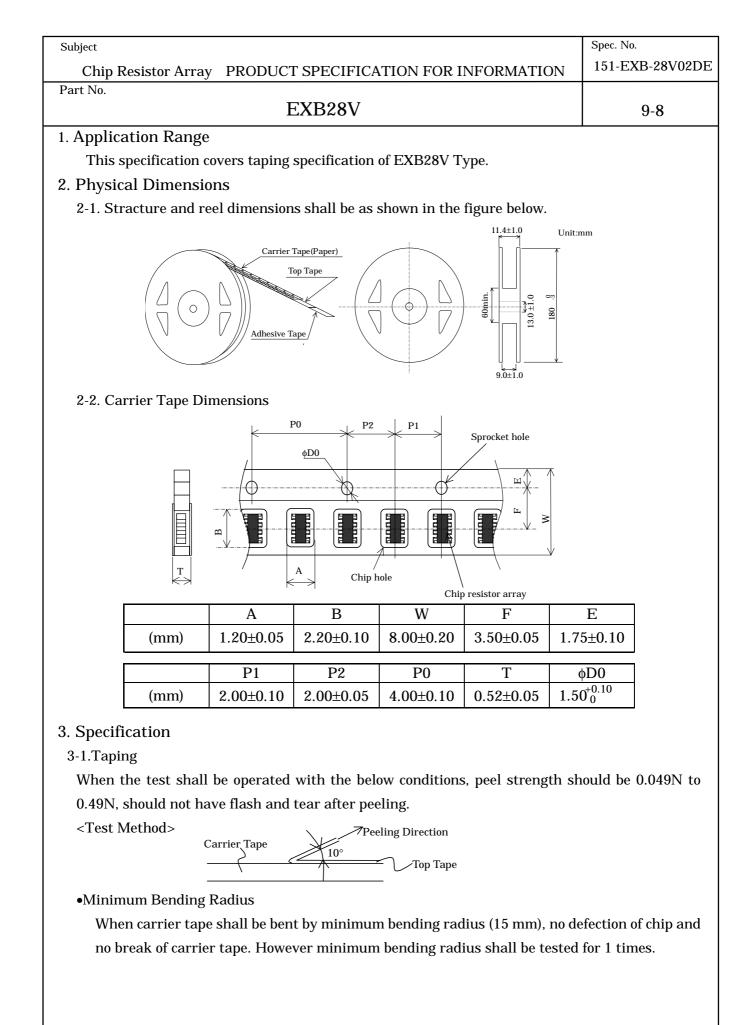
Production Plant :Fukui matsushita Electronic Components Co.,Ltd..

Production Country :China

Production Plant :Tianjin matsushita Electronic Components co.,Ltd.<TMCOM>

Production Country :Malaysia

Production Plant :Matsushita Electronic Devices (M)Sdn.Bhd.<MEDEM>



Subject	Spec. No.
Chip Resistor Array PRODUCT SPECIFICATION FOR INFORMATION	151-EXB-28V02DE
Part No. EXB28V	9-9
•Resistance to climate	
When resistors shall be exposed at 60 °C $\pm$ 2 °C, 90 %RH to 95 %RH	for 120 hours, no
defection of chip and no break off carrier tape.	
When the top tape shall be peeled, tape should not have flash and tear.	
3-2. Quantity in Taping: 10,000 pcs. / reel	
3-3. Tape packaging	
•Resistor side shall be facing upward.	
•Chip resistor shall not be sticking to top tape and bottom tape.	
•Chip resistors shall be easy to take out from carrier tape and chip hole or spre have flash and break.	ocket hole shall not
4. Outer Packaging	
Quantity: 20reels(Max.200,000 pcs.)	
Таре	
Marking	
•When packaging quantity does not reach max quantity, the remaining em buried with buffer material.	pty space shall be

•When quantity shall be few, alternative packaging methods may used. No problem must occur during the exportation of the product..

### 5. Marking

•Side of reel(Marking shall be on one side.)

(1)Part name (2)Part number (3)Quantity (4)Lot number (5)Maker name •Packaging box

(1)Customer name(2)Part name(3)Part number(4)Customer part number(5)Quantity(6)Maker name

